NE/SA5090

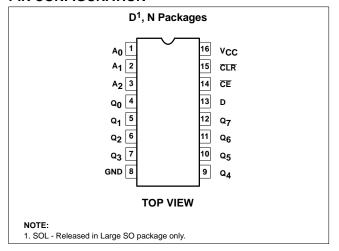
DESCRIPTION

The NE/SA5090 addressable relay driver is a high-current latched driver, similar in function to the 9934 address decoder. The device has 8 open-collector Darlington power outputs, each capable of 150mA load current. The outputs are turned on or off by respectively loading a logic "1" or logic "0" into the device data input. The required output is defined by a 3-bit address. The device must be enabled by a $\overline{\text{CE}}$ input line which also serves the function of further address decoding. A common clear input, $\overline{\text{CLR}}$, turns all outputs off when a logic "0" is applied. The device is packaged in a 16-pin plastic or Cerdip package.

FEATURES

- 8 high-current outputs
- Low-loading bus-compatible inputs
- Power-on clear ensures safe operation
- Will operate in addressable or demultiplex mode
- Allows random (addressed) data entry
- Easily expandable
- Pin-compatible with 9334 (Siliconix or Fairchild)

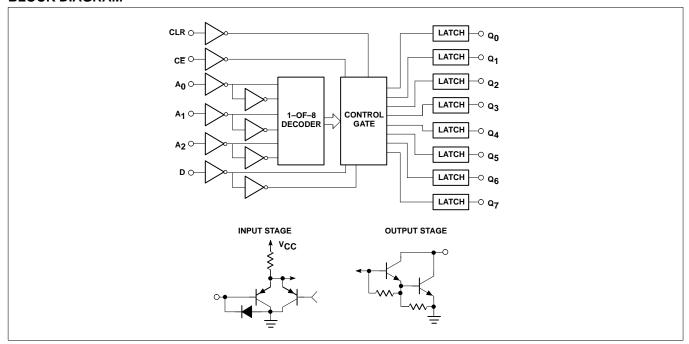
PIN CONFIGURATION



APPLICATIONS

- Relay driver
- Indicator lamp driver
- Triac trigger
- LED display digit driver
- Stepper motor driver

BLOCK DIAGRAM



NE/SA5090

PIN DESIGNATION

PIN NO.	SYMBOL	NAME AND FUNCTION
1-3	A ₀ -A ₂	A 3-bit binary address on these pins defines which of the 8 output latches is to receive the data.
4-7, 9-12	Q ₀ -Q ₇	The 8 device outputs.
13	D	The data input. When the chip is enabled, this data bit is transferred to the defined output such that: "1" turns output switch "ON" "0" turns output switch "OFF"
14	CE	The chip enable. When this input is low, the output latches will accept data. When CE goes high, all outputs will retain their existing state, regardless of address of data input condition.
15	CLR	The clear input. When CLR goes low all output switches are turned "OFF". The high data input will override the clear function on the addressed latch.

ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
16-Pin Plastic Small Outline Large (SOL) Package	0 to +70°C	NE5090D	0171B
16-Pin Plastic Dual In-Line Package (DIP)	0 to +70°C	NE5090N	0406C
16-Pin Plastic Dual In-Line Package (DIP)	-40 to +85°C	SA5090N	0406C
16-Pin Plastic Small Outline Large (SOL) Package	-40 to +85°C	SA5090D	0171B

TRUTH TABLE

		INPL	JTS			OUTPUTS					MODE			
CL	C	D	Α	Α	Α	Q	Q	Q	Q	Q	Q	Q	Q	
R	E		0	1	2	0	1	2	3	4	5	6	7	
L	Н	Χ	Χ	Χ	Χ	Н	Н	Н	Н	Н	Н	Н	Н	Clear
L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	
L	L	Н	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	
L	L	L	Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Demultiplex
L	L	Н	Н	L	L	Н	L	Н	Н	Н	Н	Н	Н	
L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	
L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L	
Н	Н	Χ	Χ	Χ	Χ	Q _N .	1 —						-	Memory
Н	L	L	L	L	L	Н	Q_N						-	
Н	L	Н	L	L	L	L	Q_{N}	N-1					-	
Н	L	L	Н	L	L	Q _N .			N-1				-	Addressable Latch
Н	L	Н	Н	L	L	Q _N .	1 L	Q	N-1					
Н	L	L	Н	Н	Н	Q _{N-}	1 —					-	- Н	
Н	L	Н	Н	Н	Н	Q _{N-}	1 —					->	► L	

NOTES:

X=Don't care condition

Q_{N-1}=Previous output state L=Low voltage level/"ON" output state H=High voltage level/"OFF" output state

NE/SA5090

ABSOLUTE MAXIMUM RATINGS

 T_A =25°C, unless otherwise specified.

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7	V
V _{IN}	Input voltage	-0.5 to +15	V
V _{OUT}	Output voltage	0 to +30	V
I _{GND}	Ground current	500	mA
I _{OUT}	Output current Each output	200	mA
P _D	Maximum power dissipation, T _A =25°C (still-air) ¹ N package	1712	mW
	D package	1315	mW
T _A	Ambient temperature range	0 to +70	°C
TJ	Junction temperature	150	°C
T _{STG}	Storage temperature range	-65 to +150	°C
T _{SOLD}	Lead soldering temperature (10sec. max)	300	°C

NOTES:

1. Derate above 25°C at the following rates:

F package at 11.1mW/°C

N package at 13.7mW/°C

D package at 10.5mW/°C

DC ELECTRICAL CHARACTERISTICS

 V_{CC} = 4.75V to 5.25V, 0°C \leq T_{A} \leq +70°C, unless otherwise specified. 1

SYMBOL	PARAMETER	TEST COMPITIONS	LIMITS			LINUT
STMBOL	PARAMETER	TEST CONDITIONS	Min	Тур	Max	UNIT
	Input voltage					
V_{IH}	High		2.0			V
V_{IL}	Low				0.8	
	Output voltage					
V_{OL}	Low	I _{OL} =150mA, T _A =25°C		1.05	1.30	V
		Over temperature			1.50	
	Input current					
I _{IH}	High	$V_{IN}=V_{CC}$		<1.0	10	μΑ
I _{IL}	Low	V _{IN} =0V		-3.0	-250	
I _{OH}	Leakage current	V _{OUT} =28V,		5	250	μΑ
	Supply current					
I _{CCL}	All outputs low	V _{CC} =5.25V		35	60	mA
I _{CCH}	All outputs high			22	50	
P_{D}	Power dissipation	No output load			315	mW

1. All typical values are at V_{CC}=5V and T_A=25°C

NE/SA5090

SWITCHING CHARACTERISTICS

V_{CC}=5V, T_A=25°C, V_{OUT}=5V, I_{OUT}=100MA, V_{IL}=0.8V, V_{IH}=2.0V.

SYMBOL	PARAMETER	ТО	FROM	MIN	TYP	MAX	UNIT
	Propagation delay time						
t _{PLH}	Low-to-high ¹	Output	CE		900	1800	ns
t _{PHL}	High-to-low ¹				130	260	
t _{PLH}	Low-to-high ²				920	1850	
		Output	Data				ns
t _{PHL}	High-to-low ²				130	260	
t _{PLH}	Low-to-high ³				900	1800	
		Output	Address				ns
t _{PHL}	High-to-low ³				130	260	
t _{PLH}	Low-to-high ⁴				920	1850	
		Output	CLR				ns
t _{PHL}	High-to-low ⁴						
Switching	setup requirements						
+	Setup time high	Chip enable	High data	40			ns
t _{S(H)}	Setup time low	Chip enable	Low data	50			115
t _{S(A)}	Address setup time	Chip enable	Address	40			ns
tu/u)	Hold time high	Chip enable	High data	10			ns
t _{H(H)}	Hold time low	Chip enable	Low data	10			110
t _{PW(E)}	Chip enable pulse width ¹			40			ns

NOTES:

- 1. See Turn-On and Turn-Off Delays, Enable-to-Output and Enable Pulse Width timing diagram.
- 2. See Turn-On and Turn-Off Delays, Data-to-Output timing diagram.
- 3. See Turn-On and Turn-Off Delays, Address-to-Output timing diagram.
- 4. See Turn-Off Delay, Clear-to-Output timing diagram.
- See Setup and Hold Time, Data-to-Enable timing diagram.
- 6. See Setup Time, Address-to-Enable timing diagram.

FUNCTIONAL DESCRIPTION

This peripheral driver has latched outputs which hold the input date until cleared. The NE5090 has active-Low, open-collector outputs, all of which are cleared when power is first applied. This device is identical to the NE590, except the outputs can withstand 28V.

Addressable Latch Function

Any given output can be turned on or off by presenting the address of the output to be set or cleared to the three address pins, by holding the "D" input High to turn on the selected output, or by holding it Low to turn off, holding the \overline{CLR} input High, and bringing the \overline{CE} input Low. Once an output is turned on or off, it will remain so until addressed again, or until all outputs are cleared by bringing the \overline{CLR} input Low while holding the \overline{CE} input High.

Demultiplexer Operation

By holding the $\overline{\text{CLR}}$ and $\overline{\text{CE}}$ inputs Low and the "D" input High, the addressed output will remain on and all other outputs will be off.

High Current Outputs

The obvious advantage of this device over other drivers such as the 9334 and N74LS259 is the fact that the outputs of the NE5090 are each capable of 200mA and 28V. It must be noted, however, that the total power dissipation would be over 2.5W if all 8 outputs were on together and carrying 200mA each. Since the total power dissipation is limited by the package to 1W, and since power dissipation due to supply current is 0.25W, the total load power dissipation by the device is limited to 0.75W at room temperature, and decreases as ambient temperature rises.

The maximum die junction temperature must be limited to 165°C, and the temperature rise above ambient and the junction temperature are defined as:

$$T_R = \theta_{JA} \times P_D$$

 $T_J = T_A + t_R$

where

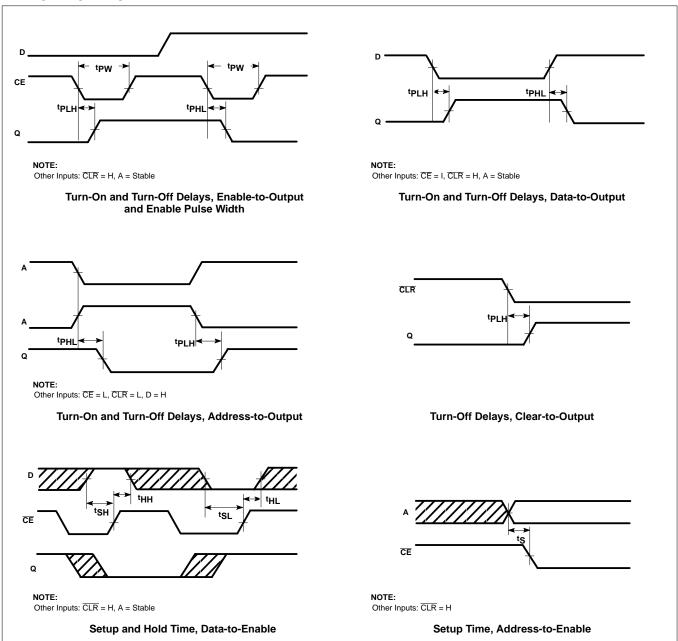
For example, if we are using the NE5090 in a plastic package in an application where the ambient temperature is never expected to rise above 50°C, and the output current at the 8 outputs, when on, are 100, 40, 50, 200, 15, 30, 80, and 10mA, we find from the graph of output voltage vs load current that the output voltages are expected to be about 0.92, 0.75, 0.78, 1.04, 0.5, 0.7, 0.9, and 0.4V, respectively. Total device power due to these loads is found to be 473.5mW. Adding the 200mW due to the power supply brings total device power dissipation to 723.5mW. The thermal resistances are 83°C,per W for plastic packages and 100°C per W for Cerdips. Using the equations above we find:

Plastic T_R =83×0.7235=60°C Plastic T_J =50+60=100°C Cerdip T_R =100×0.7235=72.4°C Cerdip T_J =50+72.4=122.4°C

Thus we find that T_J for either package is below the $165^{\circ}C$ maximum and either package could be used in this application. The graphs of total load power vs ambient temperature would also give us this same information, although interpreting the graphs would not yield the same accuracy.

NE/SA5090

TIMING DIAGRAMS

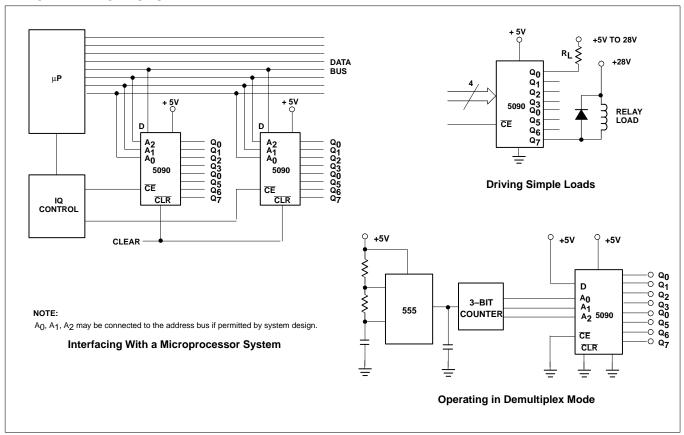


516

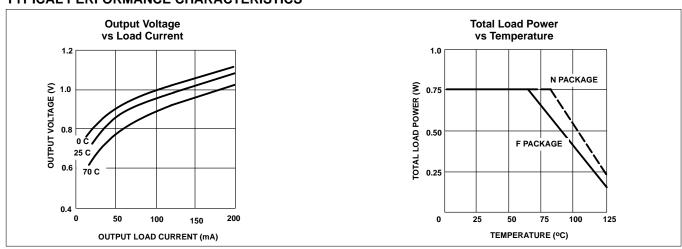
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NE/SA5090

TYPICAL APPLICATIONS



TYPICAL PERFORMANCE CHARACTERISTICS



517